



Layer Stack Legend		Material	Layer	Thickness	Dielectric Material	Type	Gerber
		Surface Material	Top Overlay			Legend	GTO
			Top Solder	0.400mil	Solder Resist	Solder Mask	GTS
		CF-004	L1_TOP	1.378mil		Signal	GTL
		Core		11.800mil	Megtron 6	Dielectric	
		Copper	L2_GND	1.400mil		Signal	G1
		Prepreg		5.197mil	Megtron 6	Dielectric	
		Prepreg		5.197mil	Megtron 6	Dielectric	
		CF-004	L3_PWR	1.378mil		Signal	G2
		Core		22.000mil	FR-4	Dielectric	
		CF-004	L4_INNER	1.378mil		Signal	G3
		Prepreg		5.197mil	Megtron 6	Dielectric	
		Prepreg		5.197mil	Megtron 6	Dielectric	
		Copper	L5_GND	1.400mil		Signal	G4
		Core		11.800mil	Megtron 6	Dielectric	
		CF-004	L6_BOT	1.378mil		Signal	GBL
		Surface Material	Bottom Solder	0.400mil	Solder Resist	Solder Mask	GBS
			Bottom Overlay			Legend	GBO
Total thickness: 75.500mil							

NOTES: UNLESS OTHERWISE SPECIFIED.

1. SURFACE FINISH: ENIG
2. SOLDERMASK COLOR: GREEN
3. SILK SCREEN COLOR: WHITE
4. COPPER WEIGHT: 1 Oz (BOTH INNER AND OUTER)
5. ALL VIAS SMALLER THAN 0.3 MM ON PAD SHOULD BE FILLED WITH NON-CONDUCTIVE EPOXY, AND THE SURFACE SHOULD BE FLAT.
6. TRACE FOR RF TRANSMISSION LINE SHOULD BE ACCURATELY ETCHED
7. IMPEDANCE CONTROL REQUIREMENT: (ALL TOLERANCE +/- 10%).
8. ALL DIMENSIONS ARE IN INCHES
9. please contact 'kunmok@berkeley.edu' (Kunmo Kim) for all other details.

Drill Table				
Symbol	Count	Hole Size	Plated Drill Layer Pair	Hole Tolerance
⊕	2541	6.000mil	Plated (Mixed)	+/-3.000mil
○	152	6.000mil	Plated L1_TOP - L6_BOT	
⊕	2	7.874mil	Plated L1_TOP - L6_BOT	
⊕	6927	8.000mil	Plated L1_TOP - L6_BOT	+/-3.000mil
▽	14	33.858mil	Plated L1_TOP - L6_BOT	
⊕	4	40.000mil	Plated L1_TOP - L6_BOT	
◇	2	52.000mil	Plated L1_TOP - L6_BOT	
□	18	63.000mil	Plated L1_TOP - L6_BOT	+/-3.000mil
⊕	24	66.929mil	Plated L1_TOP - L6_BOT	
⊕	2	91.000mil	Plated L1_TOP - L6_BOT	
☆	4	125.984mil	Plated L1_TOP - L6_BOT	
9690 Total				